



PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re U.S. Patent Application

) Art Unit: 2876

Applicant: Satoshi Kitagawa

) I hereby certify that this correspondence is being
) deposited with the United States Postal Service

Serial No.: 09/696,117

) as first class mail in an envelope addressed to:
) Commissioner of Patents, Washington, DC 20231,
) on **October 4, 2002**.

Filed: October 25, 2000

For: **MARKING METHOD FOR
SEMICONDUCTOR WAFER**

) Gerald T. Shekleton
) Gerald T. Shekleton Reg. No. 27,466

Examiner: Karl D. Frech

)

AMENDMENT

Box NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

RECEIVED
OCT 11 2002
TECHNOLOGY CENTER 2800

Dear Sir:

The Office Action of February 5, 2002 has been carefully reviewed and the following amendments
and remarks are made in response thereto:

IN THE CLAIMS:

Please amend claims 5, 6, 10, 11, and 17 to 22 as follows:

5. (Amended) The method of reproducing a mark on a semiconductor wafer according
to claim 2, wherein the predetermined mark is formed by means of a combination of dots, each dot
measuring 1 to 13 μm wide, and the substantially-effaced mark is reproduced by means of forming a
mark essentially identical with the substantially-effaced mark at another location in the vicinity fo the

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(Amended)

The method of reproducing a mark on a semiconductor wafer according
to claim 2, wherein the predetermined mark is a minute ID mark which is assigned to the semiconductor
wafer and is formed by means of a combination of dots, each dot measuring 1 to 13 μm wide, and the
substantially-effaced mark is reproduced by means of forming a mark essentially identical with the
substantially-effaced mark at another location in the vicinity of the substantially-effaced mark.